

10/523494  
DT01 Rec'd PCT/FTC 02 FEB 2005

IN THE CLAIMS

1. (Original) A method to expose a conductive coating on an inner surface of a substrate in a flexible glazing structures including a pair of substrates, comprising offsetting the substrates such that the conductive coatings on at least one inner surfaces is exposed during and after curing.
2. (Currently Amended) A method of cutting flexible glazing structures comprising:  
applying a non-conductive barrier material to a first of a pair of substrates to be laminated  
before coating with ~~LC~~liquid crystal material;  
laminating the pair of substrates with liquid crystal material therebetween; and  
cutting the laminate along the barrier lines.
3. (Original) A method to expose electrical contacts in flexible glazing structures comprising:  
cutting notches in both of a pair of substrates to be laminated;  
registering the substrates such that the notches do not overlap when the substrates are laminated together.
4. (Currently Amended) A method of cutting flexible glazing structures as in claim 2  
further comprising:  
~~applying a non-conductive barrier material to a first of a pair of substrates to be laminated~~  
~~before coating with LC;~~  
~~laminating the pair of substrates; and~~  
~~cutting the laminate along the barrier lines;~~  
shearing the first substrate to expose the second substrate along one edge of cut shape;  
and  
shearing the second substrate to expose the first substrate along another edge of cut shape.

5. (Currently Amended) A method of cutting flexible glazing structures comprising:  
laminating ~~the~~ a pair of substrates around ~~LC~~ having liquid crystal material therebetween;  
lowering the temperature of the substrates and ~~LC~~ liquid crystal material to a temperature sufficiently low to increase the viscosity of the liquid crystal material; and  
cutting the laminate, whereby due to the high viscosity, the substrates do not contact one another.
6. (Currently Amended) A method of forming shaped glazing structures comprising:  
applying barrier material to a first substrate for defining a shape;  
coating ~~LC~~ liquid crystal material on the first or a second substrate;  
cutting the first and second substrates;  
laminating the cut substrates together;  
shearing a portion of one of the substrates to expose an area of an inner conductive coating of the substrate; and  
curing the laminate.
7. (Canceled)
8. (New) A method of forming shaped glazing structures as in claim 6, wherein coating is performed prior to cutting.
9. (New) A method of forming shaped glazing structures as in claim 6, wherein cutting is performed prior to coating.